



Product Change Notification

Change Notification #: 118700-00
Change Title: 2U Hot-swap 8x3.5 inch Drive Bay Upgrade Kit, PCN 118700-00, Product Design, HSBP Interposer Implementation
Date of Publication: November 22, 2021

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	December 18, 2021
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the items included in table products affected below, due to IC shortage systems will include hot swap backplane (HSBP) identified with PBA code: G97160-373.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
2U Hot-swap 8x3.5 inch Drive Bay Upgrade Kit	A2U8X35S3HSDK1	958246	J56722-004	G97160-372	J56722-005	G97160-373

PCN Revision History:

Date of Revision: November 22, 2021	Revision Number: 00	Reason: Originally Published PCN
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118700-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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